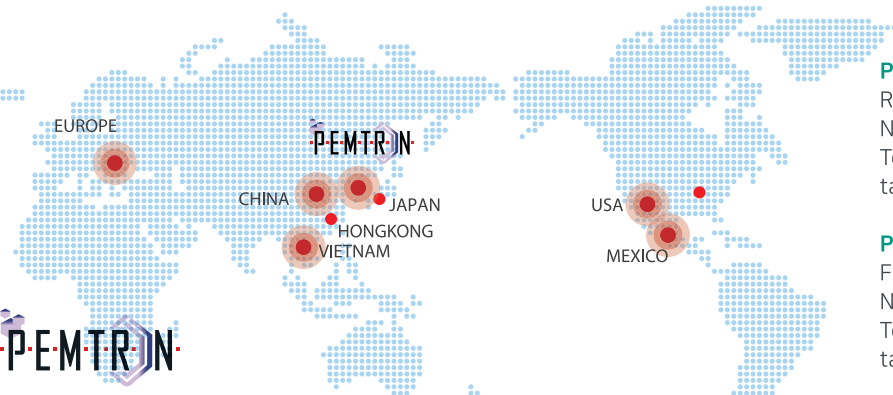
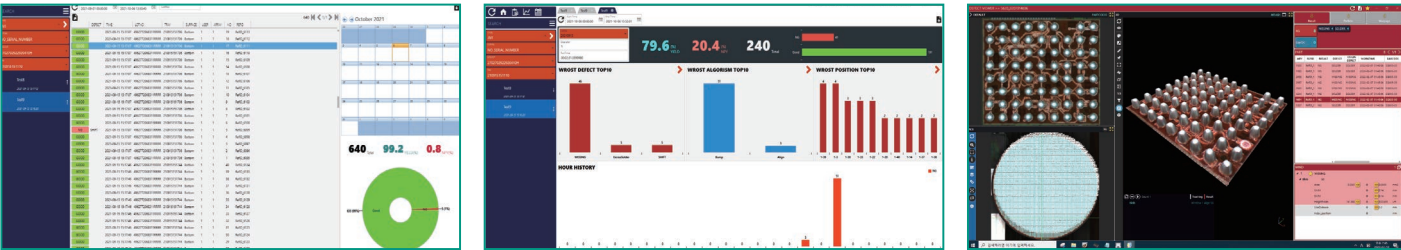


ACCURATE SPC PROCESS MANAGEMENT SYSTEM

3D image storage and NG review function without tray handling in the equipment

Capable of managing various statistical process data with the basis of accurate measurement result extracted by SPC.
Defects can be confirmed through defect history, image confirmation.

- Increasing production yield rate
- Checking Process status
- Identifying cause of defect
- Product quality improvement
- At-a-glance interface for Operator
- Data collection in Real time



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Wafer Bump
3D Vision Inspection

8800WI

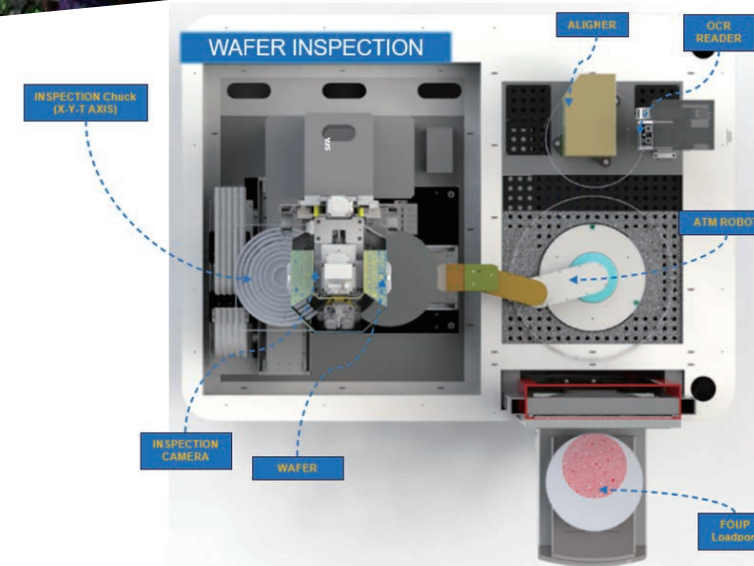
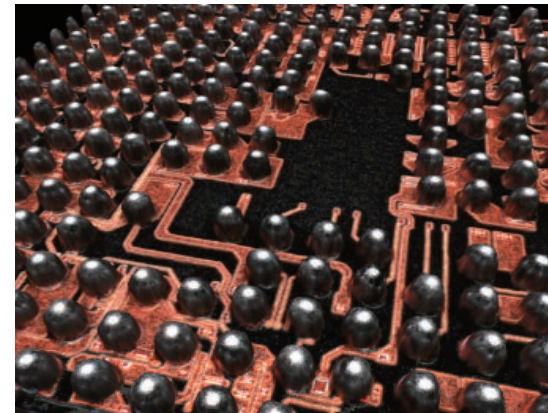


In order to provide better functions to the semiconductor industry, PEMTRON provides various inspection technologies that guarantee reliability based on 20 years of experience and technical expertise.

8800WI is designed to ensure the reliability of the final package. Our high-speed, precise, and highly reliable imaging process Micro Bump 3D measurement technology enables detection of surface defects of BUMP and WAFER, stable quality assurance for low over-detection, and high WPH through high-speed inspection. We provide world class technology to increase productivity

Function

- Inspection of all bump types including micro bumps
- High-speed vision module using high magnification camera
- Micro Bump 3D Inspection Technology /
High-resolution angular resolution of over 1um
- Securing stable quality
- AIR CHUCK Works on Both 8-inch(200mm) and
12inch(300mm) WAFER
- Users can output and monitor the designated DATA by
Using the self-developed SPC SW, such as data,
images of defects, and charts



User Customizable Solution

The system is configured for a variety of production lines, customized through dedicated solutions based on advanced technology to suit specific needs in the semiconductor industry.

With many years of field experience, our technical team develops custom algorithms for detecting and measuring sample-specific defects.

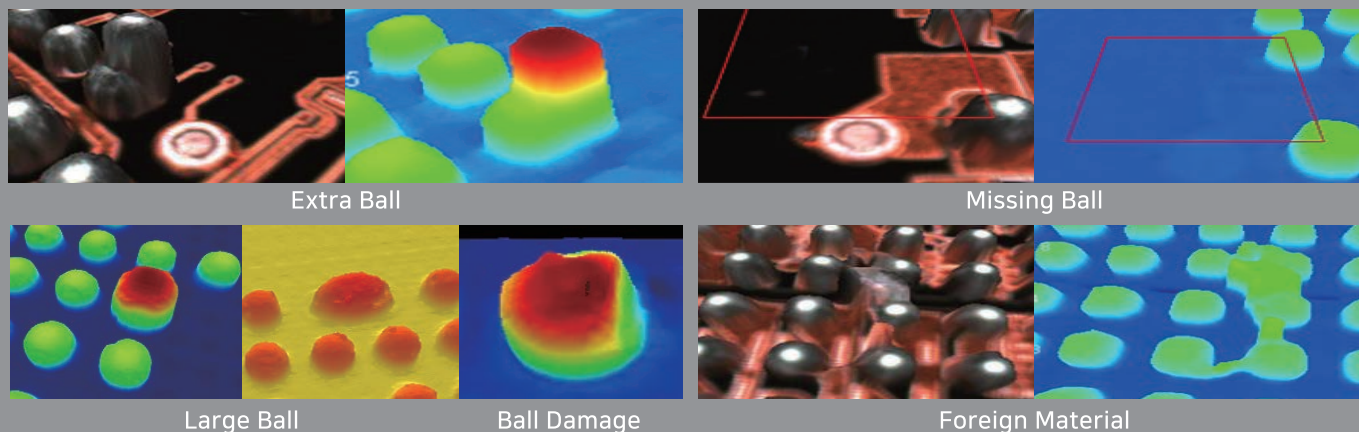
- Consistent Reliability
- Reduce resources to check and debug the defects
based on the outstanding inspection precision
- Flexible programs for operator convenience
- Software manual such as Teaching, Setup etc.
are subdivided so anyone can easily operate and
monitoring
- High resolution, advanced imaging process
- Multiple handling options for different wafer types

Rework System

- In-line system for immediate rework after
inspection
- Discharge buffer system configuration in case of
many defects

BUMP INSPECTION

BUMP inspection process using 2D & 3D inspection methods



WAFER SURFACE INSPECTION

Wafer surface inspection process using 2D & 3D inspection methods

